



2811

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application : Wusheng Yin, et al.
Application No. : 10/008,853
Filed : 11/16/01
For : NEW METHOD OF APPLYING FILLED NO-FLOW UNDERFILL
Examiner : Unassigned
Attorney's Docket : INDUM-108XX

Group Art Unit: 2811

I hereby certify that this correspondence is being deposited with the
United States Postal Service as first class mail in an envelope
addressed to: Commissioner for Patents, Washington, D.C. 20231 on
2/15/02.

By: Arthur S. Morgenstern
Arthur S. Morgenstern
Registration No. 28,244
Attorney for Applicant(s)

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

It is desired to cite for the record in this application the
enclosed references listed on the attached copy of PTO Form #1449. The
paragraph(s) marked below are applicable to this Information Disclosure
Statement.

- [X] (1) Pursuant to 37 C.F.R. § 1.97(b)(1) and (2), the attached
Information Disclosure Statement is being filed within three
months of the filing date of the above identified national
application or within three months of the date of entry of the
national stage as set forth in 37 C.F.R. § 1.491 of the above
identified application. Accordingly, applicant(s) believes that
no fee or statement under 37 C.F.R. § 1.97(e) is required.

- [] (2) Pursuant to 37 C.F.R. § 1.97(b)(3), applicant(s) believes the attached Information Disclosure Statement is being filed before the mailing date of a first Office action on the merits. Accordingly, applicant(s) believes that no fee or statement under 37 C.F.R. § 1.97(e) is required.
- [] (3) Pursuant to 37 C.F.R. § 1.97(b)(4), applicant(s) believes the attached Information Disclosure Statement is being filed before the mailing date of a first Office action after the filing of a request for continued examination under § 1.114. Accordingly, applicant(s) believes that no fee or statement under 37 C.F.R. § 1.97(e) is required.
- [] (4) Pursuant to 37 C.F.R. § 1.97(c), the attached Information Disclosure Statement is being filed before the mailing date of a final action or a notice of allowance and is accompanied by:
- [] a statement under 37 CFR § 1.97(e); or
- [] the fee set forth in § 1.17(p).

PETITION UNDER 37 CFR § 1.97(d)

- [] (5) Pursuant to 37 CFR § 1.97(d), applicant(s) hereby petitions the Commissioner to consider the attached Information Disclosure Statement which is being filed on or before payment of the issue fee. This petition is accompanied by a statement under 37 C.F.R. § 1.97(e) and the petition fee set forth in 37 C.F.R. § 1.17(p).

STATEMENT UNDER 37 C.F.R. § 1.97(e)(1)

- [] (6) The undersigned hereby states that each item of information contained in the attached Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

STATEMENT UNDER 37 C.F.R. § 1.97(e)(2)

- [] (7) The undersigned hereby states that no item of information contained in the attached Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application and, to the knowledge of the undersigned after making reasonable inquiry, no item of information contained in the attached Information Disclosure

Statement was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of this Information Disclosure Statement.

The filing of this Information Disclosure Statement is not a representation by the undersigned as to personal knowledge of the contents of every word or phrase of the material enclosed or that reliance on other suitably trained professionals has not been made.

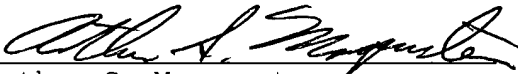
If a search report of a searching agency is enclosed identifying the nature of the relevance of each document, such a designation is deemed to satisfy 37 C.F.R. § 1.98(a)(3) even if in a foreign language because the codes are the same in all languages. However, applicant(s) does not necessarily adopt the position reflected by that report.

The Commissioner is hereby authorized to charge payment of any additional fees associated with this communication or credit any overpayment to Deposit Account No. 23-0804. Triplicate copies of this letter are enclosed.

Respectfully submitted,

WUSHENG YIN, ET AL.

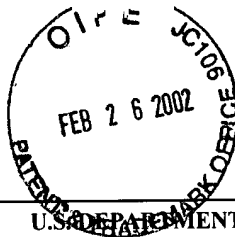
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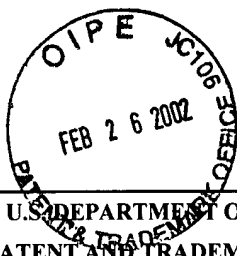
ASM/lkw/267540
Enclosure



Date: February 15, 2002

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Form PTO-1449 (REV. 07/01)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. INDUM-108XX		APPLICATION NO. 10/008,853	
INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				APPLICANT: Wusheng Yin, et al.			
				FILING DATE 11/15/01		GROUP 2811	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE*
		5,128,746	7/7/92	Pennisi et al	357	72	
		6,038,136	3/14/00	Weber	361	783	
		6,157,086	12/5/00	Weber	257	788	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
		WO 99/56312	11/4/99				
OTHER DOCUMENTS <i>(including Author, Title, Date, Pertinent Pages, etc.)</i>							
		<u>A Novel Approach to Incorporate Silica Filler into No-Flow Underfill</u> , Zhuqing Zhang, et al., School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, pp. 1-7.					
		<u>No Flow Underfill Materials for Environment Sensitive Flip-Chip Process</u> , A Dissertation Presented to The Academic Faculty, Zhuqing Zhang, Georgia Institute of Technology, June 2001, pp. 1-125.					
		<u>"No-Flow" Underfill Reliability is Here – Finally!</u> , Michael A. Previti, Cookson Semiconductor Packaging Materials, Alpharetta, GA, Session P-MT1, pp. 1-4.					
		<u>The Development of No-Flow Underfill Materials for Flip-Chip Applications</u> , Advisor Dr. C.P. Wong, Student S.H. Shi, School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, February 2, 1999.					
EXAMINER				DATE CONSIDERED			
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							



Date: February 15, 2002

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FOREIGN PATENT DOCUMENTS³							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
OTHER DOCUMENTS <i>(including Author, Title, Date, Pertinent Pages, etc.)</i>							
		Surface Mount Technology, Materials, Processes and Equipment, Carment Capillo, UNISYS Corporation, Network Computing Group, San Jose, CA, McGraw-Hill Publishing Co.					
		<u>Epoxy Flip Chip Flux PK-001</u> , Indium Corporation of America, Form No. 97727 R0.					
		<u>Pb-Free Epoxy Flip Chip Flux PK-002</u> , Indium Corporation of America, Form No. 97728 R0.					
EXAMINER				DATE CONSIDERED			
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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